

DB101S THRU DB107S

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DB101S THRU DB107S

1.0A Miniature Glass Passivated Single-Phase Surface Mount Bridge Rectifiers-50-1000V

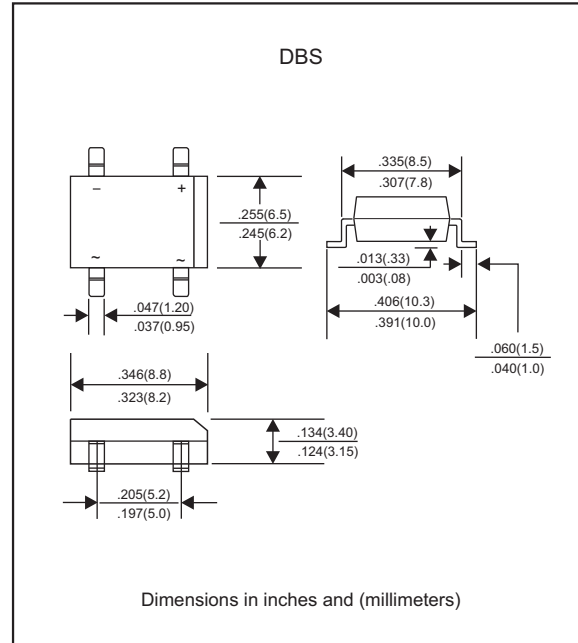
Features

- Surge overload ratings to 30 amperes peak
- Save space on printed circuit board
- Ideal for automated replacement
- Reliable low cost construction utilizing molded plastic technology results in inexpensive product
- Glass passivated chip junctions
- Lead-free parts meet RoHS requirements
- UL recognized file # E321971
- Suffix "-H" indicates Halogen free parts, ex. DB101S-H

Mechanical data

- Epoxy:UL94-V0 rated flame retardant
- Case : Molded plastic, DBS
- Terminals : Solder plated, solderable per MIL-STD-750, Method 2026
- Polarity : marked on body
- Mounting Position : Any
- Weight : Approximated 0.38 gram

Package outline



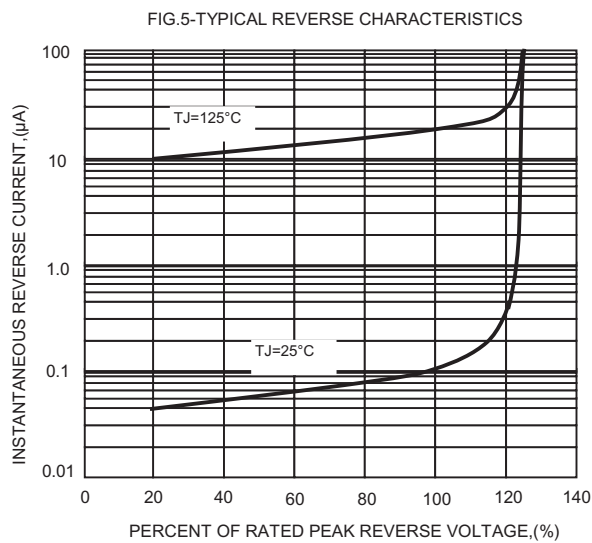
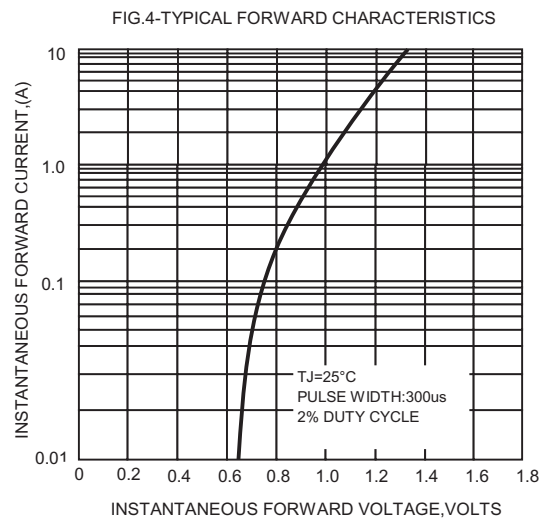
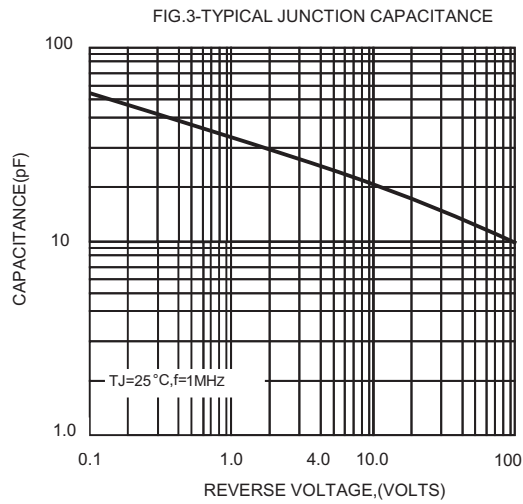
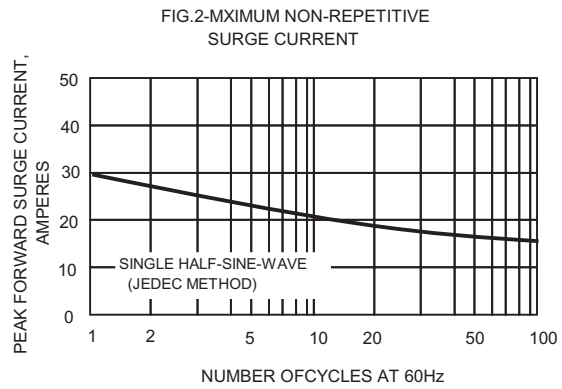
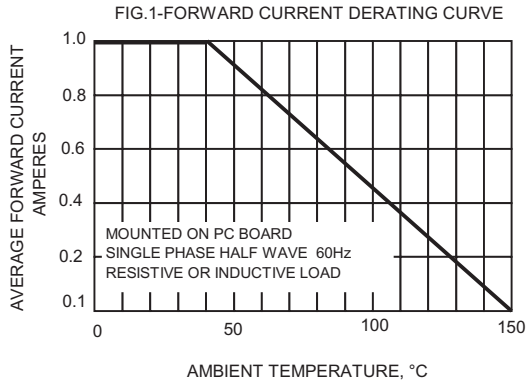
Maximum ratings and Electrical characteristics (AT $T_A=25^{\circ}\text{C}$ unless otherwise noted)

PARAMETER	CONDITIONS	Symbol	MIN.	TYP.	MAX.	UNIT
Forward rectified current	See Fig.1	I_o			1.0	A
Forward surge current	8.3ms single half sine-wave (JEDEC methode)	I_{FSM}			30	A
Reverse current	$V_R = V_{RRM} T_J = 25^{\circ}\text{C}$	I_R			10	μA
	$V_R = V_{RRM} T_J = 125^{\circ}\text{C}$				500	
I^2t Rating for fusing	$t < 8.3\text{ms}$	I^2t			3.74	A^2s
Typical junction capacitance Per element	Measured at 1.0MHz and applied reverse voltage of 4.0V DC	C_j		25		pF
Typical thermal resistance	Junction to ambient mounted on P.C.B with 0.5*0.5"(13*13mm) copper pads.	$R_{\theta JA}$		40		$^{\circ}\text{C}/\text{W}$
Storage temperature		T_{STG}	-65		+175	$^{\circ}\text{C}$

SYMBOLS	V_{RRM}^{*1} (V)	V_{RMS}^{*2} (V)	V_R^{*3} (V)	V_F^{*4} (V)	Operating temperature $T_J, (^{\circ}\text{C})$
DB101S	50	35	50	1.10	-55 to +150
DB102S	100	70	100		
DB103S	200	140	200		
DB104S	400	280	400		
DB105S	600	420	600		
DB106S	800	560	800		
DB107S	1000	700	1000		

- *1 Repetitive peak reverse voltage
- *2 RMS voltage
- *3 Continuous reverse voltage
- *4 Maximum forward voltage @ $I_F=1.0\text{A}$

Rating and characteristic curves (DB101S THRU DB107S)



DB101S THRU DB107S

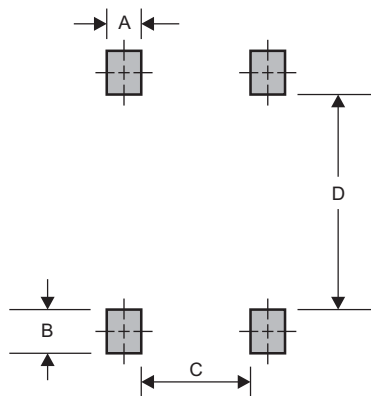
Pinning information

Simplified outline	Symbol

Marking

Type number	Marking code
DB101S	DB101S
DB102S	DB102S
DB103S	DB103S
DB104S	DB104S
DB105S	DB105S
DB106S	DB106S
DB107S	DB107S

Suggested solder pad layout

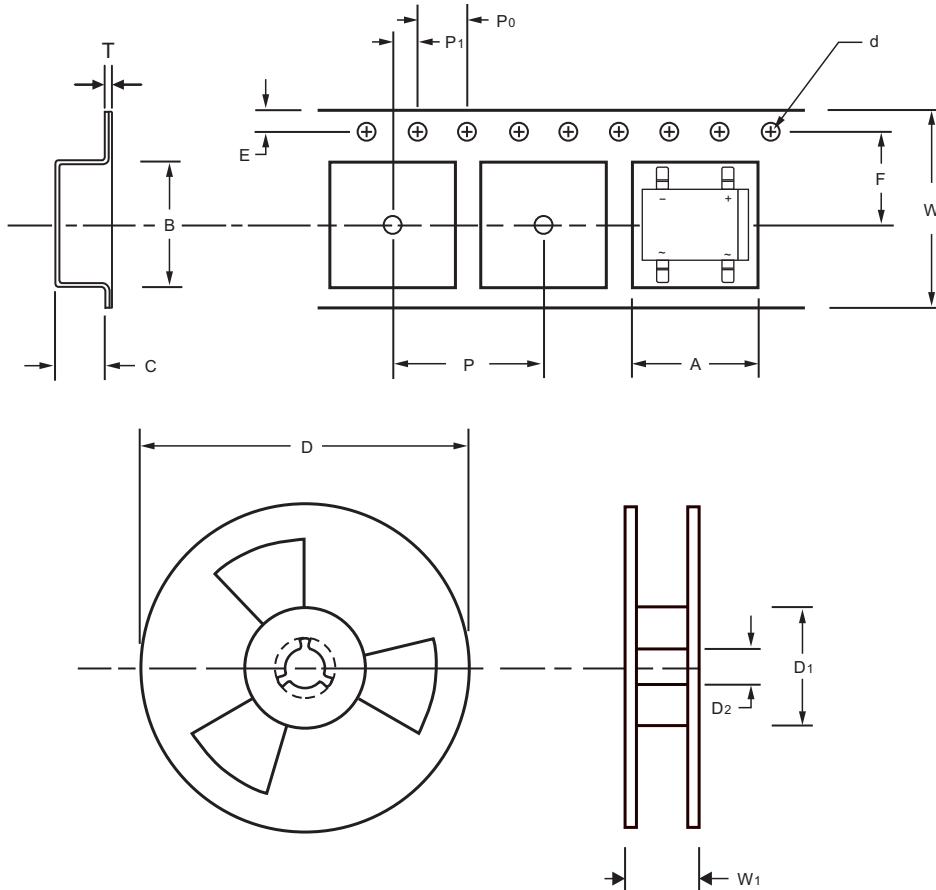


Dimensions in inches and (millimeters)

PACKAGE	A	B	C	D
DBS	0.059 (1.50)	0.047 (1.20)	0.157 (4.00)	0.291 (7.40)

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Packing information



unit:mm

Item	Symbol	Tolerance	DBS
Carrier width	A	0.1	8.64
Carrier length	B	0.1	10.41
Carrier depth	C	0.1	3.81
Sprocket hole	d	0.1	1.55
13" Reel outside diameter	D	2.0	330.00
13" Reel inner diameter	D ₁	min	50.00
7" Reel outside diameter	D	2.0	-
7" Reel inner diameter	D ₁	min	-
Feed hole diameter	D ₂	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	7.50
Punch hole pitch	P	0.1	12.00
Sprocket hole pitch	P ₀	0.1	4.00
Embossment center	P ₁	0.1	2.00
Overall tape thickness	T	0.1	0.32
Tape width	W	0.3	16.00
Reel width	W ₁	1.0	22.00

Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.

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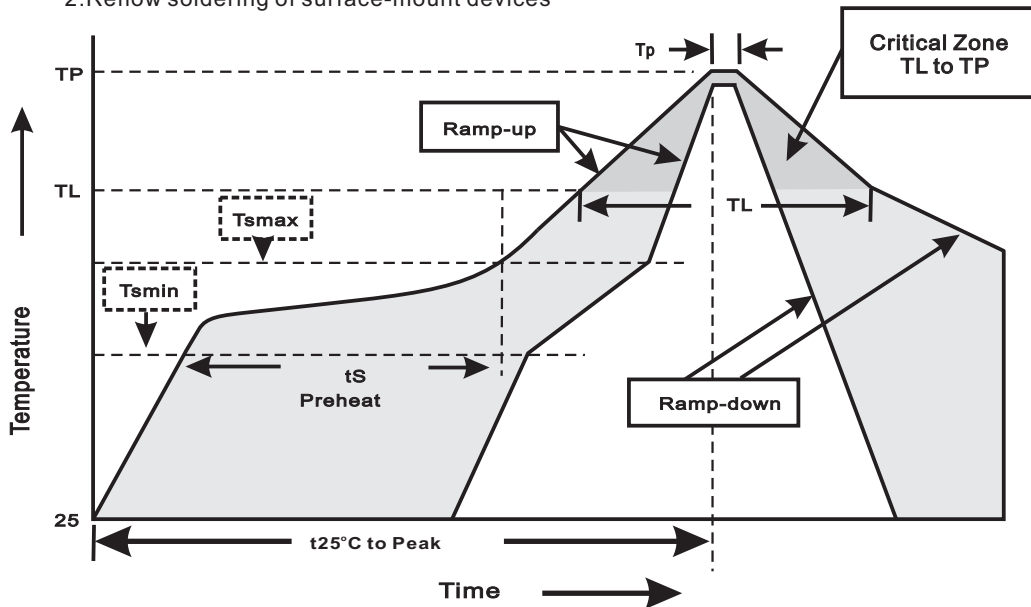
Reel packing and tube packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (m/m)	BOX (pcs)	INNER BOX (m/m)	REEL DIA, (m/m)	CARTON SIZE (m/m)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
DBS	13"	1,000	12.0	2,000	335*335*38	330	350*330*360	12,000	12.0

PACKAGE	TUBE (pcs)	TUBE SIZE (m/m)	CARTON SIZE (m/m)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
DBS	50	432*13.9*5.8	452*164*130	10,000	6.0

Suggested thermal profiles for soldering processes

- 1.Storage environment: Temperature=5°C~40°C Humidity=55%±25%
- 2.Reflow soldering of surface-mount devices



3.Reflow soldering

Profile Feature	Soldering Condition
Average ramp-up rate(TL to TP)	<3°C/sec
Preheat -Temperature Min(Tsmin) -Temperature Max(Tsmax) -Time(min to max)(ts)	150°C 200°C 60~120sec
Tsmax to TL -Ramp-upRate	<3°C/sec
Time maintained above: -Temperature(TL) -Time(tl)	217°C 60~260sec
Peak Temperature(TP)	255°C-0/+5°C
Time within 5°C of actual Peak Temperature(tp)	10~30sec
Ramp-down Rate	<6°C/sec
Time 25°C to Peak Temperature	<6minutes

DB101S THRU DB107S**High reliability test capabilities**

Item Test	Conditions	Reference
1. Solder Resistance	at 260±5°C for 10±2sec.	MIL-STD-750D METHOD-2031
2. Solderability	at 245±5°C for 5 sec.	MIL-STD-202F METHOD-208
3. High Temperature Reverse Bias	$V_R=80\%$ rate at $T_J=150^\circ\text{C}$ for 168 hrs.	MIL-STD-750D METHOD-1038
4. Forward Operation Life	Rated average rectifier current at $T_A=25^\circ\text{C}$ for 500hrs.	MIL-STD-750D METHOD-1027
5. Intermittent Operation Life	$T_A = 25^\circ\text{C}$, $I_F = I_O$ On state: power on for 5 min. off state: power off for 5 min. on and off for 500 cycles.	MIL-STD-750D METHOD-1036
6. Pressure Cooker	15P _{SIG} at $T_A=121^\circ\text{C}$ for 4 hrs.	JESD22-A102
7. Temperature Cycling	-55°C to +125°C dwelled for 30 min. and transferred for 5min. total 10 cycles.	MIL-STD-750D METHOD-1051
8. Forward Surge	8.3ms single half sine-wave , one surge.	MIL-STD-750D METHOD-4066-2
9. Humidity	at $T_A=85^\circ\text{C}$, RH=85% for 1000hrs.	MIL-STD-750D METHOD-1021
10. High Temperature Storage Life	at 175°C for 1000 hrs.	MIL-STD-750D METHOD-1031